Figure 6 shows formation of a conductor pattern including a circuit pattern upon the insulation film for formation of an LGA package of comparatively large size.

Figure 7 is a magnified drawing of a part of FIG. 6.

Figure 8 is a flow chart showing manufacturing steps for a semiconductor package according to the present invention.

Figure 9 a-e are side views corresponding to each of the steps of FIG. 8.

Figure 10 shows a pattern structure upon thermoplastic insulation film of conventional construction used for production of a semiconductor package.

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REFERENCE NUMERALS AND SYMBOLS AS SHOWN IN THE FIGURES

p	pitch of through holes
L	pitch of sprocket holes
10	insulation film
12	sprocket holes
14	through holes
16	circuit pattern
18	for-plating-use conductor pattern
20	main line
22	sub-line
90	semiconductor chip
92	conductor wire
94	molding
96	solder bump
98	through hole
100	dicing blade
102	sprocket hole
104	dicing table